

# DDR4 miniDIMM Sockets, 22.5° Angled and Vertical SMT, Halogen-free

**molex**<sup>®</sup>

Angled DDR4 miniDIMM socket saves nearly half the overhead space of the vertical equivalent in enterprise computing and networking memory applications

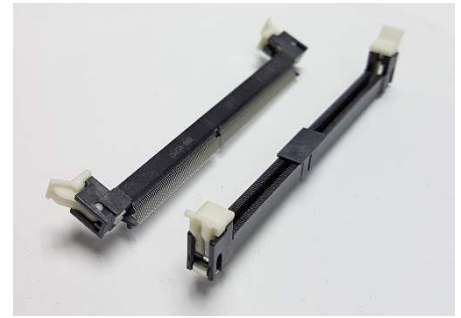
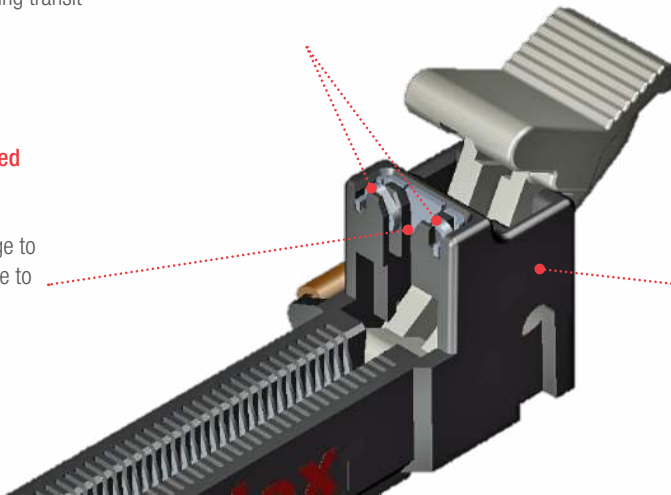
## Features and Advantages

### Metal grips on housing towers (patent pending)

Reduce shock or vibration to mounted memory modules during transit

### Metal-reinforced latch tower housing

Prevents damage to tower bridge due to wear and tear

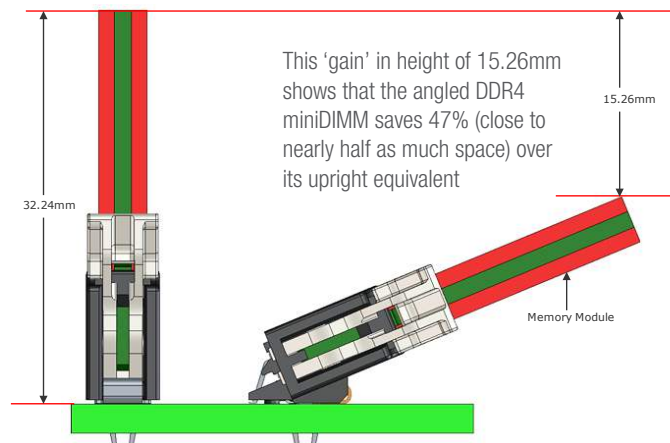


(Left to right) 22.5°-angled and Vertical SMT DDR4 miniDIMM sockets

### Halogen-free housing

Meets eco-friendly environmental requirements

The 22.5° angled DDR4 miniDIMM socket offers highly robust mating and usability features for reliable operations



The 22.5° angled DDR4 miniDIMM socket save almost half as much vertical space than its upright equivalent with module mounted

## Applications

### Data/Communications

- High-end computing
- Personal computers
- RAID / Storage

### Telecommunications/Networking

- Network Operations Center
- Infrastructure



Data Center



Network Operations Center

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## Specifications

### REFERENCE INFORMATION

Packaging: Tray  
Mates With JEDEC MO-309 Memory Modules  
UL File Number: E29179 (151105)  
CSA File Number: 1699020 (LR19980) (151105)  
Designed In: Millimeters  
RoHS: Yes  
Halogen Free: Yes  
Glow Wire Compliant: No

### ELECTRICAL

Voltage (max.): 29 Volts AC (RMS) / DC  
Current (max.): 0.75A per pin  
Low Level Contact Resistance:  
25 milliohms (151134)  
20 milliohms (151105)  
Dielectric Withstanding Voltage: 500V AC  
Insulation Resistance (min.): 1 Megohm

### MECHANICAL

Module Insertion Force (with latches): 150.0N max.  
Module Rip-out Force (min.): 3.6kgf  
Module Unmating Force: 2.02kgf (for 288 circuits)  
Insertion Force to PCB: 25N (max.)  
Terminal Retention Force (min.):  
300gf (per pin); 8.0N (per forklock)  
Latch Actuation Force (max.): 35N per latch  
Durability: 25 cycles

### PHYSICAL

Housing: LCP, Glass-filled, UL94V-0, Black  
Latch: Polyamide, Glass-filled, UL94V-0, Black  
Contact: Copper Alloy  
Plating: Contact Area:  
0.76 micron Gold (Au) over 1.25micron Nickel (Ni)  
Solder Area: 2.54micron Tin (Sn) over  
1.25micron Nickel (Ni)  
PCB hold-down: 2.54micron Tin (Sn) over  
1.25micron Nickel (Ni)  
Operating Temperature: -55 to 85°C

## Ordering Information

Series No.	Description
151134	22.5°-Angled, SMT
151105	Vertical, SMT

[www.molex.com/link/ddr4.html](http://www.molex.com/link/ddr4.html)